

**SCOPE: CMOS, TTL-COMPATIBLE ANALOG MULTIPLEXER**

<u>Device Type</u>	<u>Generic Number</u>
01	DG528A(x)/883B
02	DG529A(x)/883B

**Case Outline(s).** The case outlines shall be designated in Mil-Std-1835 and as follows:

<u>Outline Letter</u>	<u>Mil-Std-1835</u>	<u>Case Outline</u>	<u>Package Code</u>
K	GDIP1-T18 or CDIP2-T18	18 LEAD CERDIP	J18
Z	CQCC1-N20	20-Pin Ceramic LCC	L20

**Absolute Maximum Ratings**

Voltage Referenced to V<sup>-</sup>

V <sup>+</sup> .....	44V
GND .....	25V
Digital Inputs, V <sub>S</sub> , V <sub>D</sub> .....	(-V) -2V to (V <sup>+</sup> ) +2V or 20mA, whichever occurs first
Current, Any terminal except S or D .....	30mA
Continuous Current, S or D .....	20mA
Peak Current (Pulsed at 1ms, 10% duty cycle max) .....	50mA
Lead Temperature (soldering, 10 seconds) .....	+300°C
Storage Temperature .....	-65°C to +150°C

Continuous Power Dissipation $\frac{1}{}$ .....	T <sub>A</sub> = +70°C
18 lead CERDIP (derate 10.5mW/°C above +70°C) .....	842mW
20 lead LCC (derate 9.1mW/°C above +70°C) .....	727mW
Junction Temperature T <sub>J</sub> .....	+150°C
Thermal Resistance, Junction to Case, $\theta_{JC}$ :	
Case Outline 18 lead CERDIP .....	45°C/W
Case Outline 20 lead LCC .....	20°C/W
Thermal Resistance, Junction to Ambient, $\theta_{JA}$ :	
Case Outline 18 lead CERDIP .....	95°C/W
Case Outline 20 lead LCC .....	110°C/W

**Recommended Operating Conditions.**

Ambient Operating Range (T <sub>A</sub> ) .....	-55°C to +125°C
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NOTE 1: All leads are soldered or welded to PC board.

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TABLE 1. ELECTRICAL TESTS**

TEST	Symbol	CONDITIONS	Group A Subgroup	Device type	Limits Min	Limits Max	Units
		-55 °C ≤T <sub>A</sub> ≤ +125°C $\overline{\text{V}}_{+}=+15\text{V}, \text{V}_{-}=-15\text{V}, \underline{\text{V}}_{\text{GND}}=\underline{\text{V}}_{\text{WR}}=0\text{V},$ $\text{RS}=2.4\text{V}, \text{V}_{\text{AH}}=2.4\text{V}, \text{V}_{\text{AL}}=0.8\text{V}$ Unless otherwise specified					
<b>SWITCH</b>							
Analog-Signal Range	V <sub>ANALOG</sub>	V <sub>S</sub> =±15V NOTE 3	1,2,3	All	-15	15	V
Drain-Source ON Resistance	r <sub>DS(ON)</sub>	I <sub>S</sub> =-200μA, V <sub>D</sub> =±10V, V <sub>AL</sub> =0.8V, V <sub>AH</sub> =2.4V, Sequence each switch ON	1,3 2	All		400 500	Ω
Source OFF Leakage Current	I <sub>S(OFF)</sub>	V <sub>S</sub> =10mA, V <sub>D</sub> =-10V, V <sub>EN</sub> =0V	1 2	All	-1 -50	1 50	nA
Source OFF Leakage Current	I <sub>S(OFF)</sub>	V <sub>S</sub> =-10mA, V <sub>D</sub> =10V, V <sub>EN</sub> =0V	1 2	All	-1 -50	1 50	nA
Drain OFF Leakage Current	I <sub>D(OFF)</sub>	V <sub>S</sub> =±10mA, V <sub>D</sub> =±10V, V <sub>EN</sub> =0V	1	All	-10	10	nA
			2	01	-200	200	
			2	02	-100	-100	
Drain ON Leakage Current	I <sub>D(ON)</sub>	V <sub>D</sub> =V <sub>S</sub> =±10V, V <sub>AL</sub> =0.8V, V <sub>AH</sub> =2.4V, V <sub>EN</sub> =2.4V, NOTE 3, 4	1	All	-10	10	nA
			2	01	-200	200	
			2	02	-100	100	
<b>INPUT</b>							
Input Current/Voltage High	I <sub>AH</sub>	V <sub>IN</sub> = 2.4V	1,3 2	All	-1 -30	1	μA
		V <sub>IN</sub> =15V	1,3 2	All	-1	1 30	
Input Current/Voltage Low	I <sub>AL</sub>	V <sub>EN</sub> =0V, 2.4V; V <sub>A</sub> =0V, $\overline{\text{V}}_{\text{A}}=\overline{\text{V}}_{\text{WR}}=\overline{\text{V}}_{\text{RS}}=0\text{V}$	1,3 2	All	-1 -30	1	μA
<b>SUPPLY</b>							
Positive Supply Current	I+	V <sub>EN</sub> =V <sub>A</sub> =0V	1	All		2.5	mA
Negative Supply Current	I-	V <sub>EN</sub> =V <sub>A</sub> =0V	1	All	-1.5		mA
<b>DYNAMIC</b>							
Transition Time	t <sub>TRANS</sub>	Figure 1	9 10,11	All		1.0 1.5	μs
Enable and Write Turn ON Time	t <sub>ON</sub> $\overline{\text{EN}}, \overline{\text{WR}}$	See Figures 2 and 3	9 10,11	All		1.5 2.0	μs
Enable and Write Turn OFF Time	t <sub>OFF</sub> $\underline{\text{EN}}, \underline{\text{RS}}$	See Figures 2 and 3	9 10,11	All		1.5 2.0	μs

TEST	Symbol	CONDITIONS		Group A Subgroup	Device type	Limits Min	Limits Max	Units
		-55 °C ≤ T <sub>A</sub> ≤ +125 °C	V <sub>+</sub> =+15V, V <sub>-</sub> =-15V, V <sub>RS</sub> =2.4V, GND=WR=0V, V <sub>AH</sub> =2.4V, V <sub>AL</sub> =0.8V Unless otherwise specified					
<b>MINIMUM INPUT TIMING</b>								
WR Pulse Width	t <sub>WW</sub>	Figure 7		9,10,11	All	300		ns
AX, EN Data valid to WR	t <sub>DW</sub>	(Stabilization Time) Figure 7		9,10,11	All	180		ns
AX, EN Data valid after WR	t <sub>WD</sub>	(Hold Time) Figure 7		9,10,11	All	30		ns
RS Pulse Width	t <sub>RS</sub>	Figure 7; V <sub>S</sub> =5V NOTE 5		9,10,11	All	500		ns

NOTE 2: Guaranteed by design.

NOTE 3: Sequence each switch on.

NOTE 4: ID(ON) is leakage drom driver into on switch

NOTE 5: Reset pulse period must be at least 50µs during and after power-on.

#### TRUTH TABLE

#### TERMINAL CONNECTION

A2	A1	A0	EN	WR	RS	DG528A ON SWITCH	TERMINAL NUMBER	01 DG528A	01 DG528A	02 DG529A	02 DG529A
X	X	X	X	↑	1	*		J18	L20	J18	L20
X	X	X	X	X	0	**					
X	X	X	0	0	1	None	1	WR	NC	WR	NC
0	0	0	1	0	1	1	2	A0	WR	A0	WR
0	0	1	1	0	1	2	3	EN	A0	EN	A0
0	1	0	1	0	1	3	4	V-	EN	V-	EN
0	1	1	1	0	1	4	5	S1	VSS	S1A	VSS
1	0	0	1	0	1	5	6	S2	S1	S2A	S1A
1	0	1	1	0	1	6	7	S3	S2	S3A	S2A
1	1	0	1	0	1	7	8	S4	S3	S4A	S3A
1	1	1	1	0	1	8	9	D	S4	DA	S4A
							10	S8	D	DB	DA
							11	S7	NC	S4B	NC
							12	S6	S8	S3B	DB
	A1	A0	EN	WR	RS	DG529A ON SWITCH	13	S5	S7	S2B	S4B
	X	X	X	↑	1	*	14	V+	S6	S1B	S3B
	X	X	X	0	1	**	15	GND	S5	V+	S2B
	X	X	0	0	1	None	16	A2	VDD	GND	S1B
	0	0	1	0	1	1	17	A1	GND	A1	VDD
	0	1	1	0	1	2	18	RS	A2	RS	GND
	1	0	1	0	1	3	19		A1		A1
	1	1	1	0	1	4	20		RS		RS

NOTE: Logic "1": V<sub>AH</sub> ≥ 2.4V

Logic "0": V<sub>AL</sub> ≥ 0.8V

\* LATCHING: Maintains previous switch conditions

\*\*RESET: None (latches cleared)

<b>ORDERING INFORMATION:</b>			
DG528AK/883B	18 CDIP	DG529AK/883B	18 CDIP
DG528AZ/883B	20 LCC	DG529AZ/883B	20 LCC

**FIGURE 1: TRANSITION TIME TEST CIRCUIT:** See Commercial Data Sheet

**FIGURE 3: Enable  $t_{ON}/t_{OFF}$  Test Time Circuit:** See Commercial Data Sheet

**FIGURE 4: Write Turn-On Time Test Circuit:** See Commercial Data Sheet

**FIGURE 5: Write Turn-Off Time Test Circuit:** See Commercial Data Sheet

**FIGURE 7: Typical Timing Diagrams:** See Commercial Data Sheet

## QUALITY ASSURANCE

Sampling and inspection procedures shall be in accordance with MIL-Prf-38535, Appendix A as specified in Mil-Std-883.

Screening shall be in accordance with Method 5004 of Mil-Std-883. Burn-in test Method 1015:

1. Test Condition, A, B, C, or D.
2. TA = +125°C minimum.
3. Interim and final electrical test requirements shall be specified in Table 2.

Quality conformance inspection shall be in accordance with Method 5005 of Mil-Std-883, including Groups A, B, C, and D inspection.

Group A inspection:

1. Tests as specified in Table 2.
2. Selected subgroups in Table 1, Method 5005 of Mil-Std-883 shall be omitted.

Group C and D inspections:

- a. End-point electrical parameters shall be specified in Table 1.
- b. Steady-state life test, Method 1005 of Mil-Std-883:
  1. Test condition A, B, C, D.
  2. TA = +125°C, minimum.
  3. Test duration, 1000 hours, except as permitted by Method 1005 of Mil-Std-883.

**TABLE 2. ELECTRICAL TEST REQUIREMENTS**

Mil-Std-883 Test Requirements	Subgroups per Method 5005, Table 1
Interim Electric Parameters Method 5004	1
Final Electrical Parameters Method 5005	1*, 2, 3, 9
Group A Test Requirements Method 5005	1, 2, 3, 9, 10**, 11**
Group C and D End-Point Electrical Parameters Method 5005	1

\* PDA applies to Subgroup 1 only.

\*\* Subgroups 10 and 11, if not tested shall be guaranteed to the limits of Table 1.